



DEPARTMENTS

-  AEI NEWS **08**
-  IN VIEW THIS MONTH **10**
-  BUSINESS STRATEGY **52**
-  PRODUCT NEWS **57**

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp; Subscription e-mail: circulationmanila@dempa.co.jp.

The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <https://www.dempa.co.jp/en/pdfs/orderform.pdf>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

TAIWAN: International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 **KOREA:** Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **PHILIPPINES:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-8845-0906 Fax: +63-2-8845-1829

President & Publisher: Tsutomu Hirayama
Copyright © 2020 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in China.

SPECIAL REPORT

- Open Source Collaboration to Shape Future of 5G **12**
- New Demand Trends to Boost Slack Capacitor Market **14**
- IC Process Materials Makers Invest Actively in EUV **17**
- Continental Sets Off NVIDIA-Powered Supercomputer for Vehicle AI System **18**

TECH FOCUS

- Nichicon Levels up Heat Resistance of In-Vehicle Capacitors **20**
- Makers Amplify Parts Features to Reinforce Role of Inverters **23**
- Technology Makes Accurate Circuit Simulation for SiC-MOSFETs **24**
- Aluminum Electrolytic Capacitors Evolve with Market Demand **26**

SMTs: IN REVIEW

28

COMPONENT MATERIALS

32

TECHNOLOGY HIGHLIGHT

- Testing Coronavirus Antigens Taps Quartz Crystal Equipment **34**
- Fluoresin-Based FPC Stands out in High Frequency **34**
- Novel Fabrication to Improve Performance of SiC Power Transistors **35**

PRODUCT HIGHLIGHT

- OMRON's New ToF Sensor Module Enables 3D Distance Depth **36**
- Compact, High-Functional Sensors Eye Popular Markets **38**

SHOW PREVIEW

- International Electronics Circuit Exhibition 2020 **39**

IN FOCUS: SEMICON Taiwan

40

SHOW REPORT

- SID 2020 **46**

ZOOM-IN

48

INDUSTRY REPORT

50

TOP INTERVIEW

- Lelon Taps Growth Fields to Cushion Pandemic Impacts **54**

MANUFACTURING FRONT

- OTAX Thai Facility Charts Recovery Path, Boosts Capacity **56**